

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJP03N90M1
Package Type :	TO-220-3L

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Lead Frame	Cu	7440-50-8	99.67%	67.8479%
	Ag	7440-60-8	0.20%	
	Fe	7439-89-6	0.10%	
	P	7723-14-0	0.03%	
Wafer	Si	7440-21-3	98.00%	0.2825%
	SiO2	7631-86-9	0.05%	
	Ag	7440-22-4	0.05%	
	Al	7429-90-5	0.90%	
	others	N/A	1.00%	
Wire1	Al	7429-90-5	99.995%	0.1328%
	others	/	0.005%	
Wire2	Cu	7429-90-5	99.995%	0.0569%
	others	/	0.005%	
Solder	Pb	7439-92-1	92.50%	0.1139%
	Sn	7440-31-5	5.00%	
	Ag	7440-22-4	2.50%	
Compound	SiO2	14808-60-7	82.00%	29.2743%
	Epoxy Resin	29690-82-2	10.00%	
	Phenol Resin	9003-35-4	7.50%	
	Carbon black	1333-86-4	0.50%	
Plating	Sn	7440-31-5	99.96%	2.2916%
	Others	NA	0.04%	

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.